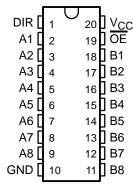
SCBS013H - SEPTEMBER 1998 - REVISED MAY 2002

- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- ESD Protection Exceeds JESD 22
 2000-V Human-Body Model (A114-A)

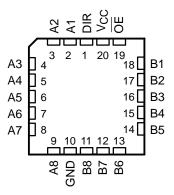
description

These octal bus transceivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

SN54BCT245 . . . J OR W PACKAGE SN74BCT245 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54BCT245 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74BCT245N	SN74BCT245N	
0°C to 70°C	SOIC - DW	Tube	SN74BCT245DW	BCT245	
	SOIC - DW	Tape and reel	SN74BVT245DWR		
	SOP - NS	Tape and reel	SN74BCT245NSR	BCT245	
	SSOP – DB Tape and reel		SN74BCT245DBR	BT245	
	TSSOP – PW	Tape and reel	SN74BCT245PWR	BT245	
	CDIP – J	Tube	SNJ54BCT245J	SNJ54BCT245J	
–55°C to 125°C	CFP – W	Tube	SNJ54BCT245W	SNJ54BCT245W	
	LCCC – FK	Tube	SNJ54BCT245FK	SNJ54BCT245FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



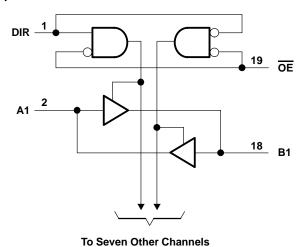
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



FUNCTION TABLE

INP	UTS	OPERATION			
ŌĒ	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			

logic diagram (positive logic)



absolute maximum ratings over	er operating free-air temperature	range (unless otherwise noted)†
-------------------------------	-----------------------------------	---------------------------------

Supply voltage range, V _{CC} –0.	5 V 10 / V
Input voltage range, V _I : Control inputs (see Note 1)	5 V to 7 V
I/O ports (see Note 1)	V to 5.5 V
Voltage range applied to any output in the disabled or power-off state, V _O	5 V to 7 V
Voltage range applied to any output in the high state, V _O	V to V _{CC}
Current into any output in the low state, IO: SN54BCT245	96 mA
SN74BCT245	. 128 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	. 70°C/W
DW package	. 58°C/W
N package	. 69°C/W
NS package	. 60°C/W
PW package	. 83°C/W
Storage temperature range, T _{stq} –65°C	c to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

			SN54BCT245		SN74BCT245			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
٧ _{IH}	High-level input voltage		2			2			V
V _{IL}	Low-level input voltage				0.8			0.8	V
lιΚ	Input clamp current				-18			-18	mA
lau	High level output ourrent	A port			-3			-3	mA
ЮН	High-level output current	B port			-12			-15	mA
la.	Low lovel output ourrent	A port			20			24	mA
IOL	Low-level output current	B port			48			64	IIIA
TA	Operating free-air temperature	_	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN	SN54BCT245			SN74BCT245		
Ρ/	ARAMETER	1E9	I CONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT
٧ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
	A port	V45V	I _{OH} = -1 mA	2.5	3.4		2.5	3.4		
	A port	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		
۷он			$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3		V
	B port	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					
			$I_{OH} = -15 \text{ mA}$				2	3.1		
	A port	V _{CC} = 4.5 V	I _{OL} = 20 mA		0.3	0.5				
VOL	Apon	VCC = 4.5 V	$I_{OL} = 24 \text{ mA}$					0.35	0.5	v
VOL	B port	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V
	Броп	VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.42	0.55	
1.	A or B port	V _{CC} = 5.5 V,	V _I = 5.5 V			1			1	mA
i _l	Control input	VCC = 5.5 V,	V = 3.5 V			0.1			0.1	
ıt	A or B port	V _{CC} = 5.5 V,	V _I = 2.7 V			70			70	μΑ
I _{IH} ‡	Control input	VCC = 5.5 V,	V - 2.7 V			20			20	μΑ
ı †	A or B port	V _{CC} = 5.5 V,	V _I = 0.5 V			-0.65			-0.65	mA
I _{IL} ‡	Control input	VCC = 0.5 V,	V = 0.5 V			-1.2			-1.2	ША
1 8	A port	V _{CC} = 5.5 V,	VO = 0	-60		-150	-60		-150	mA
los§	B port	VCC = 5.5 V,	VO = 0	-100		-225	-100		-225	ША
ICCL	A to B	V _{CC} = 5.5 V			57	90		57	90	mA
ICCH	A to B	V _{CC} = 5.5 V			36	57		36	57	mA
ICCZ		V _{CC} = 5.5 V			10	15		10	15	mA
Ci	Control input	$V_{CC} = 5 V$,	$V_I = 2.5 \text{ V or } 0.5 \text{ V}$		7			7		pF
C:-	A to B	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		9			9		pF
C _{io}	B to A	\ \(\cdot \)	VO = 2.5 V OI 0.5 V		12			12		ρı

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

SN54BCT245, SN74BCT245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _l R1 R2	CC = 5 V = 50 pl I = 500 S 2 = 500 S L = 25°C	F, Ω, Ω,	C R R	L = 50 p 1 = 500 2 = 500	Ω,		UNIT
			′1	BCT245		SN54B	CT245	SN74B	CT245	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
tPLH	A or B	B or A	1	4.4	6	1	7.2	1	7	ns
^t PHL	AUIB	BULK	1.5	4.8	6.6	1.5	7.6	1.5	7	115
^t PZH	ŌĒ	A or B	1.5	8	9.4	1.5	11.2	1.5	10.9	ns
^t PZL	OE	AOIB	1.5	8	10.2	1.5	11.8	1.5	11.6	115
^t PHZ	ŌĒ	A or B	1.5	5.8	8.3	1.5	9.7	1.5	9.3	ns
t _{PLZ}	J. J.	AUB	1.5	5.1	7.8	1.5	9.6	1.5	9.1	115

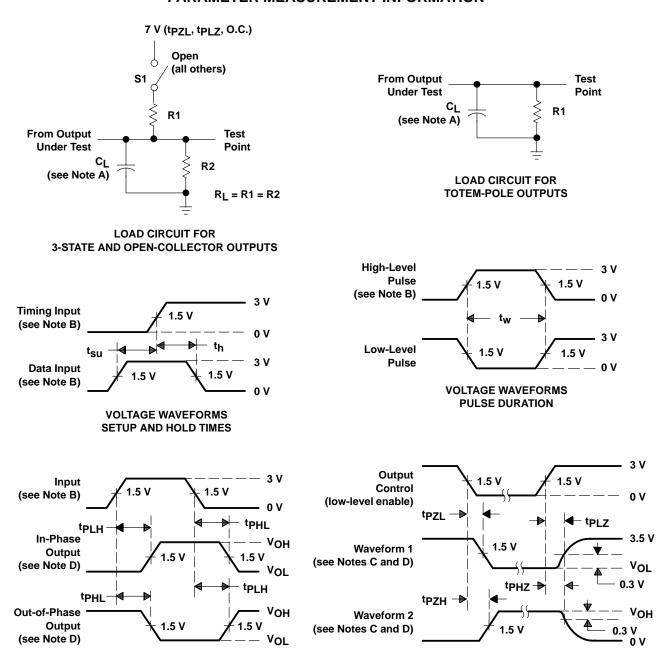
[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)

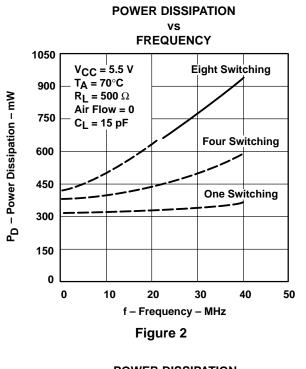
- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $t_f = t_f \leq 2.5$ ns, duty cycle = 50%.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.

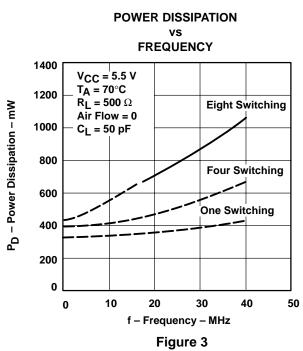
Figure 1. Load Circuit and Voltage Waveforms

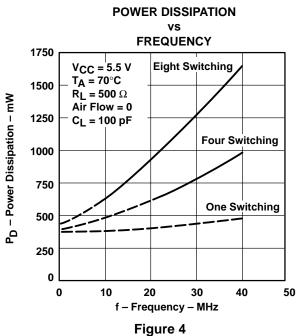


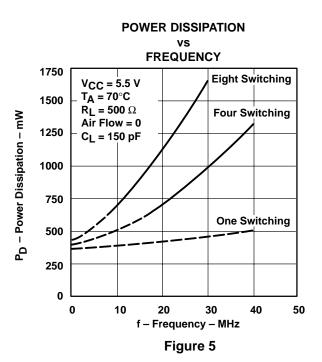
TYPICAL CHARACTERISTICS[†]

Figures 2 through 5 show the typical power dissipation for an SN74BCT245 over variations in outputs switching, output frequency, and capacitive load.











[†]The dashed lines are for the DB package only.





v.ti.com 4-Mar-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-9051401M2A	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
5962-9051401MRA	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
5962-9051401MSA	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC
SN74BCT245DBLE	OBSOLETE	SSOP	DB	20		None	Call TI	Call TI
SN74BCT245DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT245DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT245DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74BCT245NSR	ACTIVE	SO	NS	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74BCT245PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74BCT245PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SNJ54BCT245FK	ACTIVE	LCCC	FK	20	1	None	Call TI	Level-NC-NC-NC
SNJ54BCT245J	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
SNJ54BCT245W	ACTIVE	CFP	W	20	1	None	Call TI	Level-NC-NC-NC

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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